

P-Channel Enhancement Mode Field Effect Transistor

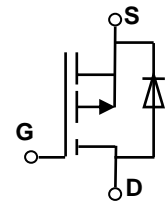
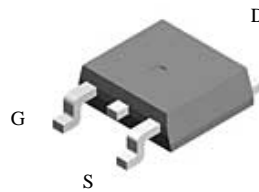
FEATURES

- Super high dense cell design for low $R_{DS(ON)}$
- Rugged and reliable
- Simple drive requirement
- TO-252 package

PRODUCT SUMMARY		
V_{DSS}	I_D	$R_{DS(ON)}$ (m Ω) Typ
-30V	-12A	43 @ $V_{GS}=-10V$
		70 @ $V_{GS}=-4.5V$



NOTE: The MT9435L is available in a lead-free package



ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous ^a @ $T_j=125^\circ C$ - Pulse d^b	I_D	-12	A
	I_{DM}	-42	A
Drain-source Diode Forward Current ^a	I_S	-1.7	A
Maximum Power Dissipation ^a	P_D	50	W
Operating Junction and Storage Temperature Range	T_j, T_{STG}	-55 to 150	$^\circ C$

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to Ambient ^a	$R_{th JA}$	50	$^\circ C/W$
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ELECTRICAL CHARACTERISTICS (TA=25°C unless otherwise noted)

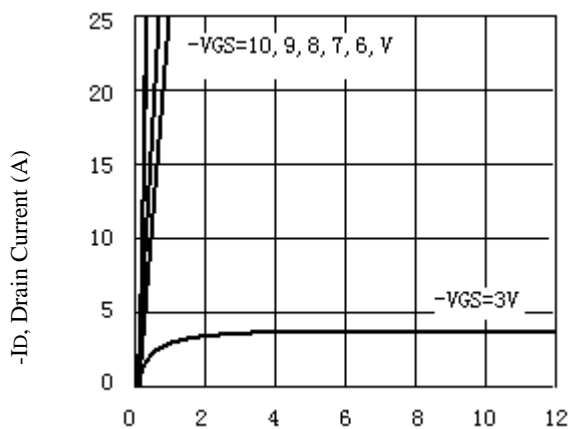
Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	-30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-24V, V _{GS} =0V			-1	μA
Gate-Body Leakage	I _{GSS}	V _{GS} =±20V, V _{DS} =0V			±100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1	-1.5	-2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-12A		43	50	mΩ
		V _{GS} =-4.5V, I _D =-5.6A		70	85	
Forward Transconductance	g _{FS}	V _{GS} =-5V, I _D =-12A		5		S
DAYNAMIC CHARACTERISTICS						
Input Capacitance	C _{ISS}	V _{DS} =-15V, V _{GS} =0V f=1.0MHz		582		pF
Output Capacitance	C _{OSS}			125		pF
Reverse Transfer Capacitance	C _{RSS}			86		pF
SWITCHING CHARACTERISISTICS						
Turn-On Delay Time	t _{D(ON)}	V _{DD} =-15V I _D =-12A, V _{GEN} =-4.5V R _L =10ohm R _{GEN} =6ohm		9		ns
Rise Time	t _r			10		ns
Turn-Off Delay Time	t _{D(OFF)}			38		ns
Fall Time	t _f			23		ns
Total Gate Charge	Q _g	V _{DS} =-15V, I _D =-1A V _{GS} =-10V		11.7		nC
Gate-Source Charge	Q _{gs}			2.1		nC
Gate-Drain Charge	Q _{gd}			2.9		nC

ELECTRICAL CHARACTERISTICS (TA=25°C unless otherwise noted)

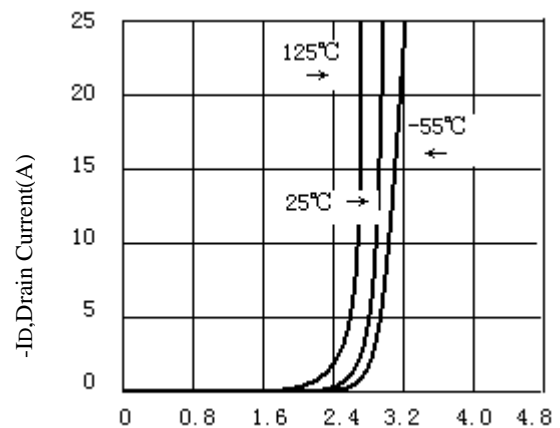
Parameter	Symbol	Condition	Min	Typ	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS						
Diode Forward Voltage	VSD	VGS=0V, IS=-1.7A		-0.84	-1.2	V

Notes

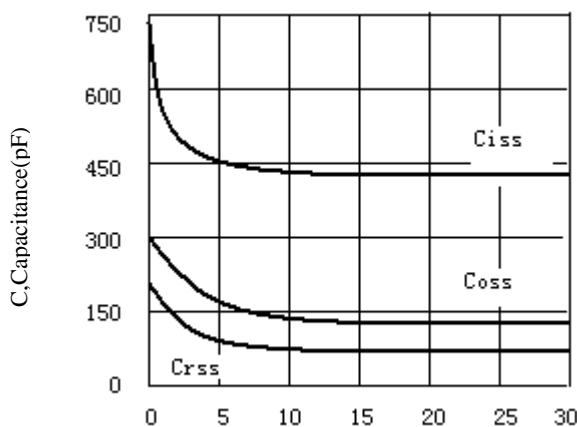
- a. Surface Mounted on FR4 Board, $t \leq 10\text{sec}$
- b. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$
- c. Guaranteed by design, not subject to production testing.



- VDS, Drain-to-Source Voltage (V)
Figure 1. Output Characteristics



-VGS, Gate-to-source Voltage (V)
Figure 2. Transfer Characteristics



- VGS, Drain-to Source Voltage
Figure 3. Capacitance

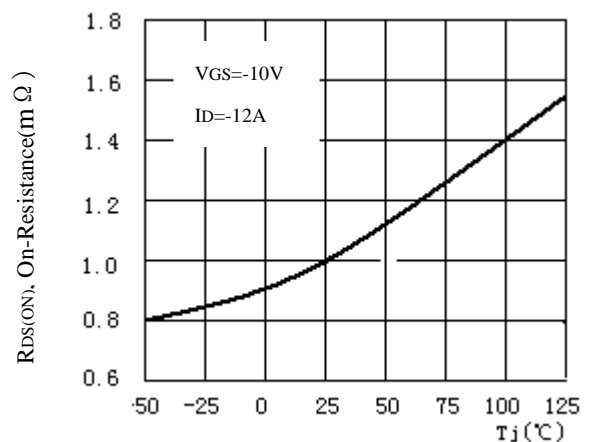
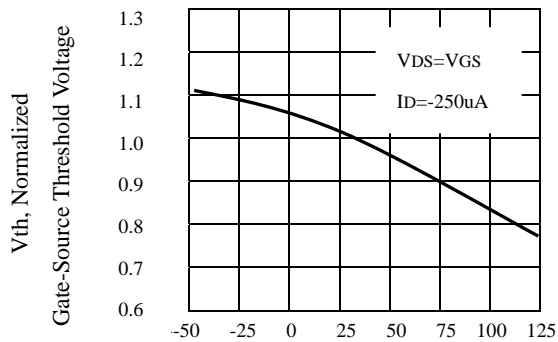
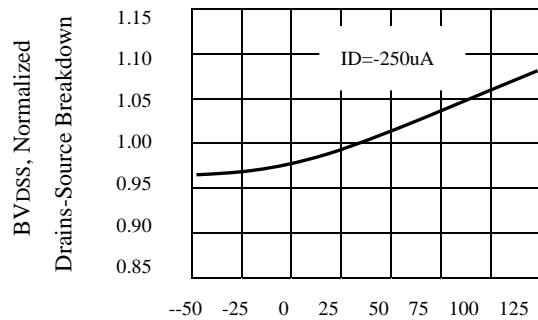


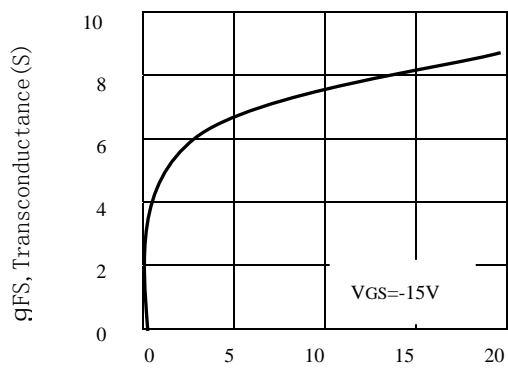
Figure 4. On-Resistance Variation with Temperature



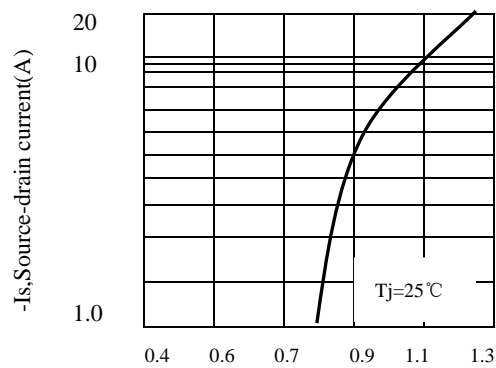
Tj, Junction Temperature(°C)
Figure5.Gate Threshold Variation
With Temperature



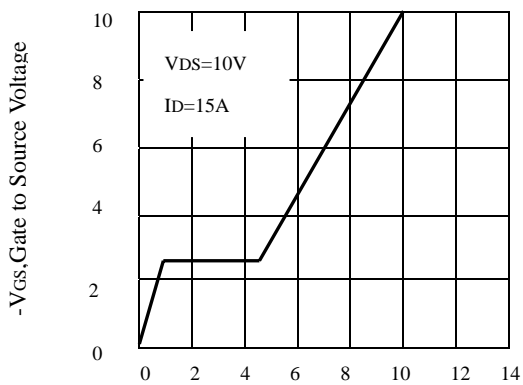
Tj, Junction Temperature (°C)
Figure6.Breakdown Voltage Variation
With Temperature



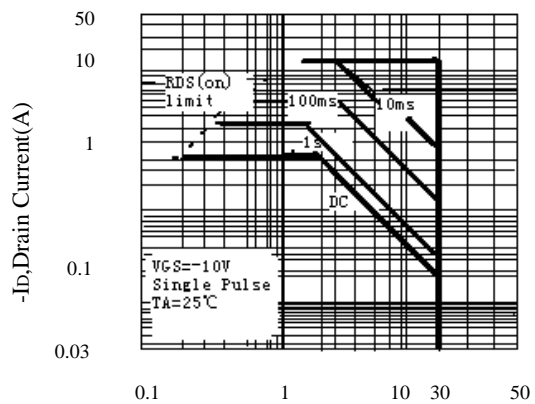
-IDS, Drain-Source Current (A)
Figure7.Transconductance Variation
With Drain Current



-VSD, Body Diode Forward Voltage
Figure8.Body Diode Forward Voltage
Variation with Source Current



Qg, Total Gate Charge (nC)
Figure9. Gate Charge



-VDS, Drain-Source Voltage(V)
Figure10.Maximum Safe Operating Area